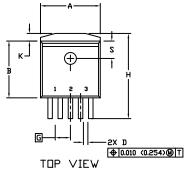


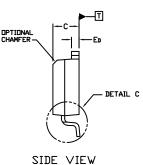


D²PAK 5-LEAD CASE 936A-02 **ISSUE E**

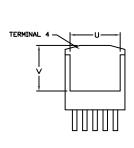
DATE 28 JUL 2021

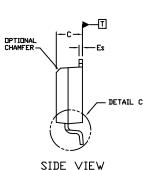






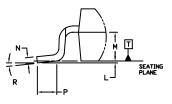
DUAL GUAGE



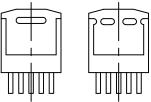


BOTTOM VIEW

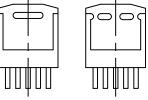
SINGLE GUAGE

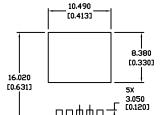


DETAIL C TIP LEADFORM ROTATED 90° CW



BOTTOM VIEW OPTIONAL CONSTRUCTIONS





PITCH RECOMMENDED MOUNTING FOOTPRINT *

5X 1.016 [0.040]

For additional information on our Pb-Free strategy and soldering details, please download the IN Seniconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

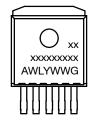
1.702 [0.067]

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCHES
- TAB CONTOUR OPTIONAL WITHIN DIMENSIONS
- DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.396	0.403	9.804	10.236
В	0.356	0.368	9.042	9.347
С	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
ED	0.045	0.055	1.143	1.397
Es	0.018	0.026	0.457	0.660
G	0.067 BSC		1.702 BSC	
Н	0.539	0.579	13.691	14.707
К	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
М	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
Р	0.058	0.078	1.473	1.981
R	•	8.	0*	8.
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
$\overline{}$	0.250 MIN		6.350 MIN	

GENERIC MARKING DIAGRAM*



= Device Code XXXXXX = Assembly Location Α WL = Wafer Lot

= Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION	D2PAK 5-I FAD		PAGE 1 OF 1

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